

# TL081, TL081A, TL081B, TL082, TL082A, TL082B TL084, TL084A, TL084B JFET-INPUT OPERATIONAL AMPLIFIERS

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- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Total Harmonic Distortion . . . 0.003% Typ
- High Input Impedance . . . JFET-Input Stage
- Latch-Up-Free Operation
- High Slew Rate . . . 13 V/ $\mu$ s Typ
- Common-Mode Input Voltage Range Includes  $V_{CC+}$

## description/ordering information

The TL08x JFET-input operational amplifier family is designed to offer a wider selection than any previously developed operational amplifier family. Each of these JFET-input operational amplifiers incorporates well-matched, high-voltage JFET and bipolar transistors in a monolithic integrated circuit. The devices feature high slew rates, low input bias and offset currents, and low offset-voltage temperature coefficient. Offset adjustment and external compensation options are available within the TL08x family.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from –40°C to 85°C. The Q-suffix devices are characterized for operation from –40°C to 125°C. The M-suffix devices are characterized for operation over the full military temperature range of –55°C to 125°C.

## ORDERING INFORMATION

$T_J$	$V_{IOmax}$ AT 25°C	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	15 mV	PDIP (P)	Tube of 50	TL081CP	TL081CP
			Tube of 50	TL082CP	TL082CP
		PDIP (N)	Tube of 25	TL084CN	TL084CN
		SOIC (D)	Tube of 75	TL081CD	TL081C
			Reel of 2500	TL081CDR	
			Tube of 75	TL082CD	TL082C
			Reel of 2500	TL082CDR	
			Tube of 50	TL084CD	TL084C
			Reel of 2500	TL084CDR	
		SOP (PS)	Reel of 2000	TL081CPSR	T081
			Reel of 2000	TL082CPSR	T082
		SOP (NS)	Reel of 2000	TL084CNSR	TL084
		TSSOP (PW)	Tube of 150	TL082CPW	T082
			Reel of 2000	TL082CPWR	
			Tube of 90	TL084CPW	T084
			Reel of 2000	TL084CPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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**description/ordering information (continued)**

**ORDERING INFORMATION**

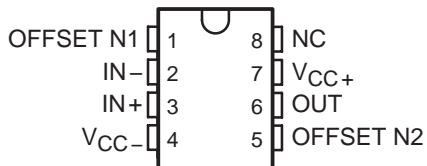
T <sub>J</sub>	V <sub>IO</sub> max AT 25°C	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	6 mV	PDIP (P)	Tube of 50	TL081ACP	TL081ACP
			Tube of 50	TL082ACP	TL082ACP
		PDIP (N)	Tube of 25	TL084ACN	TL084ACN
		SOIC (D)	Tube of 75	TL081ACD	081AC
			Reel of 2500	TL081ACDR	
			Tube of 75	TL082ACD	082AC
			Reel of 2500	TL082ACDR	
		SOIC (D)	Tube of 50	TL084ACD	TL084AC
	Reel of 2500		TL084ACDR		
	SOP (PS)	Reel of 2000	TL082ACPSR	T082A	
	SOP (NS)	Reel of 2000	TL084ACNSR	TL084A	
	3 mV	PDIP (P)	Tube of 50	TL081BCP	TL081BCP
			Tube of 50	TL082BCP	TL082BCP
		PDIP (N)	Tube of 25	TL084BCN	TL084BCN
SOIC (D)		Tube of 75	TL081BCD	081BC	
		Reel of 2500	TL081BCDR		
		Tube of 75	TL082BCD	082BC	
		Reel of 2500	TL082BCDR		
SOIC (D)		Tube of 50	TL084BCD	TL084BC	
	Reel of 2500	TL084BCDR			
-40°C to 85°C	6 mV	PDIP (P)	Tube of 50	TL081IP	TL081IP
			Tube of 50	TL082IP	TL082IP
		PDIP (N)	Tube of 25	TL084IN	TL081IN
		SOIC (D)	Tube of 75	TL081ID	TL081I
			Reel of 2500	TL081IDR	
			Tube of 75	TL082ID	TL082I
			Reel of 2500	TL082IDR	
		SOIC (D)	Tube of 50	TL084ID	TL084I
	Reel of 2500		TL084IDR		
	TSSOP (PW)	Reel of 2000	TL082IPWR	Z082	
-40°C to 125°C	9 mV	SOIC (D)	Tube of 50	TL084QD	TL084QD
			Reel of 2500	TL084QDR	
-55°C to 125°C	9 mV	CDIP (J)	Tube of 25	TL084MJ	TL084MJ
		LCCC (FK)	Reel of 55	TL084FK	TL084FK
	6 mV	CDIP (JG)	Tube of 50	TL082MJG	TL082MJG
		LCCC (FK)	Tube of 55	TL082MFK	TL082MFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

# TL081, TL081A, TL081B, TL082, TL082A, TL082B TL084, TL084A, TL084B JFET-INPUT OPERATIONAL AMPLIFIERS

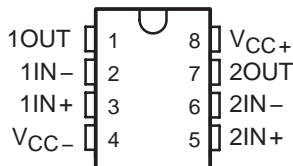
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**TL081, TL081A, TL081B**  
D, P, OR PS PACKAGE  
(TOP VIEW)

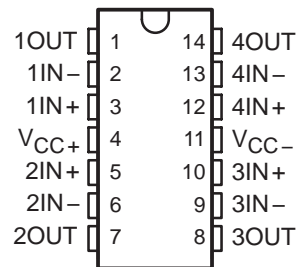


NC – No internal connection

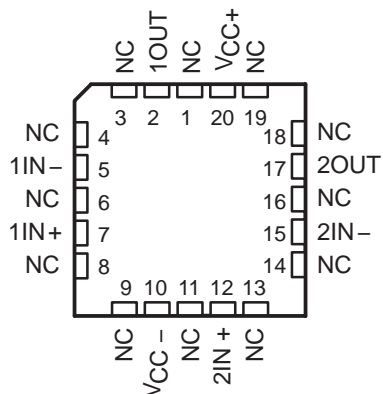
**TL082, TL082A, TL082B**  
D, JG, P, PS, OR PW PACKAGE  
(TOP VIEW)



**TL084, TL084A, TL084B**  
D, J, N, NS, OR PW PACKAGE  
(TOP VIEW)

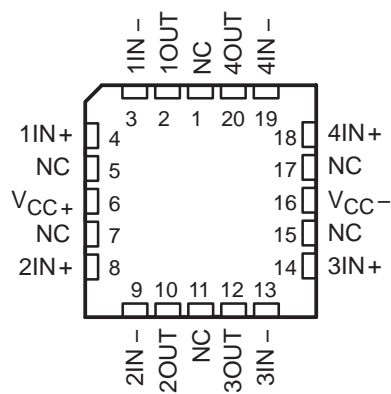


**TL082M . . . FK PACKAGE**  
(TOP VIEW)



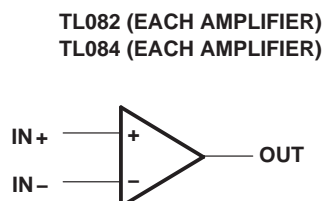
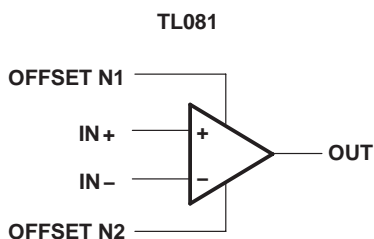
NC – No internal connection

**TL084M . . . FK PACKAGE**  
(TOP VIEW)



NC – No internal connection

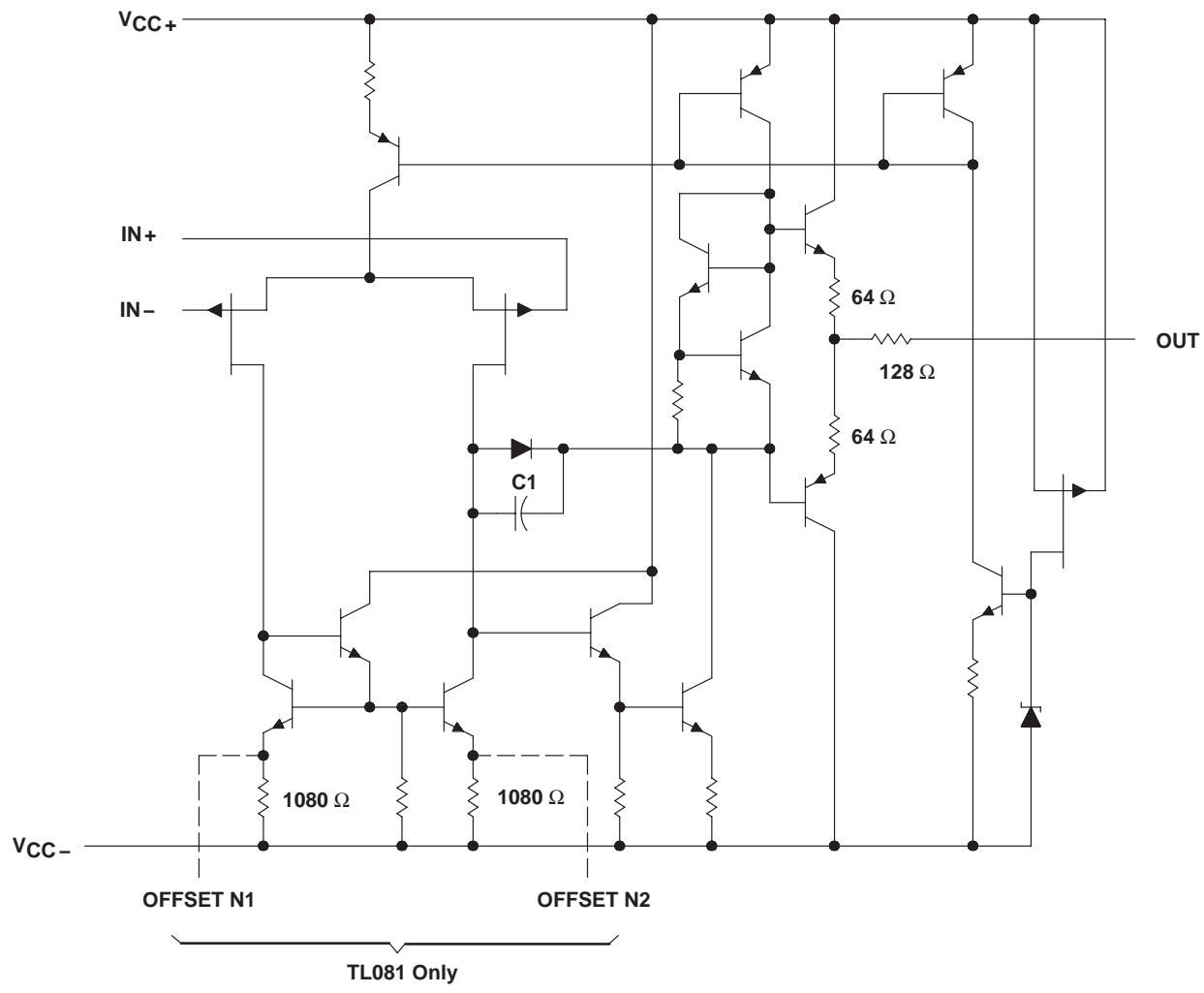
## symbols



**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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**schematic (each amplifier)**



Component values shown are nominal.



# TL081, TL081A, TL081B, TL082, TL082A, TL082B TL084, TL084A, TL084B JFET-INPUT OPERATIONAL AMPLIFIERS

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**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

	TL08_C TL08_AC TL08_BC	TL08_I	TL084Q	TL08_M	UNIT
Supply voltage, $V_{CC+}$ (see Note 1)	18	18	18	18	V
Supply voltage $V_{CC-}$ (see Note 1)	-18	-18	-18	-18	V
Differential input voltage, $V_{ID}$ (see Note 2)	$\pm 30$	$\pm 30$	$\pm 30$	$\pm 30$	V
Input voltage, $V_I$ (see Notes 1 and 3)	$\pm 15$	$\pm 15$	$\pm 15$	$\pm 15$	V
Duration of output short circuit (see Note 4)	Unlimited	Unlimited	Unlimited	Unlimited	
Continuous total power dissipation	See Dissipation Rating Table				
Operating free-air temperature range, $T_A$	0 to 70	-40 to 85	-40 to 125	-55 to 125	$^{\circ}\text{C}$
Package thermal impedance, $\theta_{JA}$ (see Notes 5 and 6)	D package (8-pin)	97	97		$^{\circ}\text{C}/\text{W}$
	D package (14-pin)	86	86		
	N package (14-pin)	76	76		
	NS package (14-pin)	80			
	P package (8-pin)	85	85		
	PS package (8-pin)	95	95		
	PW package (8-pin)	149			
	PW package (14-pin)	113	113		
Operating virtual junction temperature	150	150	150	150	$^{\circ}\text{C}$
Case temperature for 60 seconds, $T_C$	FK package			260	$^{\circ}\text{C}$
Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds	J or JG package			300	$^{\circ}\text{C}$
Storage temperature range, $T_{stg}$	-65 to 150	-65 to 150	-65 to 150	-65 to 150	$^{\circ}\text{C}$

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
- All voltage values, except differential voltages, are with respect to the midpoint between  $V_{CC+}$  and  $V_{CC-}$ .
  - Differential voltages are at  $IN+$  with respect to  $IN-$ .
  - The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
  - The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
  - Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150 $^{\circ}\text{C}$  can affect reliability.
  - The package thermal impedance is calculated in accordance with JESD 51-7.

**DISSIPATION RATING TABLE**

PACKAGE	$T_A \leq 25^{\circ}\text{C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE $T_A$	$T_A = 70^{\circ}\text{C}$ POWER RATING	$T_A = 85^{\circ}\text{C}$ POWER RATING	$T_A = 125^{\circ}\text{C}$ POWER RATING
D (14 pin)	680 mW	7.6 mW/ $^{\circ}\text{C}$	60 $^{\circ}\text{C}$	604 mW	490 mW	186 mW
FK	680 mW	11.0 mW/ $^{\circ}\text{C}$	88 $^{\circ}\text{C}$	680 mW	680 mW	273 mW
J	680 mW	11.0 mW/ $^{\circ}\text{C}$	88 $^{\circ}\text{C}$	680 mW	680 mW	273 mW
JG	680 mW	8.4 mW/ $^{\circ}\text{C}$	69 $^{\circ}\text{C}$	672 mW	546 mW	210 mW



**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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electrical characteristics,  $V_{CC\pm} = \pm 15\text{ V}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T <sub>A</sub> †	TL081C TL082C TL084C			TL081AC TL082AC TL084AC			TL081BC TL082BC TL084BC			TL081I TL082I TL084I			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V <sub>IO</sub>	Input offset voltage V <sub>O</sub> = 0 R <sub>S</sub> = 50 Ω	25°C Full range	3	15	6	3	6	3	2	3	3	6	6	mV	
α <sub>VIO</sub>	Temperature coefficient of input offset voltage V <sub>O</sub> = 0 R <sub>S</sub> = 50 Ω	Full range		18		18		18		18		18		μV/°C	
I <sub>IO</sub>	Input offset current ‡ V <sub>O</sub> = 0	25°C Full range	5	200	2	5	100	5	100	5	100	5	100	pA	
I <sub>IB</sub>	Input bias current ‡ V <sub>O</sub> = 0	25°C Full range	30	400	10	30	200	30	200	30	200	30	200	nA	
V <sub>ICR</sub>	Common-mode input voltage range	25°C	±11	-12 to 15		±11	-12 to 15		±11	-12 to 15		±11	-12 to 15	V	
V <sub>OM</sub>	Maximum peak output voltage swing	25°C Full range	±12	±13.5		±12	±13.5		±12	±13.5		±12	±13.5	V	
A <sub>V/D</sub>	Large-signal differential voltage amplification V <sub>O</sub> = ±10 V, R <sub>L</sub> ≥ 2 kΩ V <sub>O</sub> = ±10 V, R <sub>L</sub> ≥ 2 kΩ	25°C Full range	25	200	15	50	200	25	50	200	25	50	200	V/mV	
B <sub>1</sub>	Unity-gain bandwidth	25°C	3			3			3			3		MHz	
r <sub>i</sub>	Input resistance	25°C	10 <sup>12</sup>			10 <sup>12</sup>			10 <sup>12</sup>			10 <sup>12</sup>		Ω	
CMRR	Common-mode rejection ratio V <sub>IC</sub> = V <sub>ICRmin</sub> , V <sub>O</sub> = 0, R <sub>S</sub> = 50 Ω	25°C	70	86		75	86		75	86		75	86	dB	
k <sub>SVR</sub>	Supply-voltage rejection ratio (ΔV <sub>CC±</sub> /ΔV <sub>IO</sub> ) V <sub>CC</sub> = ±15 V to ±9 V, V <sub>O</sub> = 0, R <sub>S</sub> = 50 Ω	25°C	70	86		80	86		80	86		80	86	dB	
I <sub>CC</sub>	Supply current (per amplifier) V <sub>O</sub> = 0, No load	25°C	1.4	2.8		1.4	2.8		1.4	2.8		1.4	2.8	mA	
V <sub>O1</sub> /V <sub>O2</sub>	Crosstalk attenuation A <sub>V/D</sub> = 100	25°C	120			120			120			120		dB	

† All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range for T<sub>A</sub> is 0°C to 70°C for TL08\_C, TL08\_AC, TL08\_BC and -40°C to 85°C for TL08\_I.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.



**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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**electrical characteristics,  $V_{CC\pm} = \pm 15\text{ V}$  (unless otherwise noted)**

PARAMETER	TEST CONDITIONS†	$T_A$	TL081M, TL082M			TL084Q, TL084M			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$V_{IO}$ Input offset voltage	$V_O = 0, R_S = 50\ \Omega$	25°C	3	6		3	9	mV	
		Full range			9		15		
$\alpha_{VIO}$ Temperature coefficient of input offset voltage	$V_O = 0, R_S = 50\ \Omega$	Full range	18			18			$\mu\text{V}/^\circ\text{C}$
$I_{IO}$ Input offset current‡	$V_O = 0$	25°C	5	100		5	100	pA	
		125°C	20			20			nA
$I_{IB}$ Input bias current‡	$V_O = 0$	25°C	30	200		30	200	pA	
		125°C	50			50			nA
$V_{ICR}$ Common-mode input voltage range		25°C	$\pm 11$	-12 to 15		$\pm 11$	-12 to 15	V	
$V_{OM}$ Maximum peak output voltage swing	$R_L = 10\ \text{k}\Omega$	25°C	$\pm 12$	$\pm 13.5$		$\pm 12$	$\pm 13.5$	V	
	$R_L \geq 10\ \text{k}\Omega$	Full range	$\pm 12$		$\pm 12$				
	$R_L \geq 2\ \text{k}\Omega$		$\pm 10$	$\pm 12$	$\pm 10$	$\pm 12$			
$A_{VD}$ Large-signal differential voltage amplification	$V_O = \pm 10\ \text{V}, R_L \geq 2\ \text{k}\Omega$	25°C	25	200		25	200	V/mV	
	$V_O = \pm 10\ \text{V}, R_L \geq 2\ \text{k}\Omega$	Full range	15		15				
$B_1$ Unity-gain bandwidth		25°C	3			3			MHz
$r_i$ Input resistance		25°C	$10^{12}$			$10^{12}$			$\Omega$
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}, V_O = 0, R_S = 50\ \Omega$	25°C	80	86		80	86	dB	
$k_{SVR}$ Supply-voltage rejection ratio ( $\Delta V_{CC\pm}/\Delta V_{IO}$ )	$V_{CC} = \pm 15\ \text{V to } \pm 9\ \text{V}, V_O = 0, R_S = 50\ \Omega$	25°C	80	86		80	86	dB	
$I_{CC}$ Supply current (per amplifier)	$V_O = 0, \text{ No load}$	25°C	1.4	2.8		1.4	2.8	mA	
$V_{O1}/V_{O2}$ Crosstalk attenuation	$A_{VD} = 100$	25°C	120			120			dB

† All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

‡ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperatures as close to the ambient temperature as possible.

**operating characteristics,  $V_{CC\pm} = \pm 15\ \text{V}, T_A = 25^\circ\text{C}$  (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
SR Slew rate at unity gain	$V_I = 10\ \text{V}, R_L = 2\ \text{k}\Omega, C_L = 100\ \text{pF}, \text{ See Figure 1}$	8*	13		V/ $\mu\text{s}$	
	$V_I = 10\ \text{V}, R_L = 2\ \text{k}\Omega, C_L = 100\ \text{pF}, T_A = -55^\circ\text{C to } 125^\circ\text{C}, \text{ See Figure 1}$	5*				
$t_r$ Rise time	$V_I = 20\ \text{mV}, R_L = 2\ \text{k}\Omega, C_L = 100\ \text{pF}, \text{ See Figure 1}$	0.05			$\mu\text{s}$	
Overshoot factor		20			%	
$V_n$ Equivalent input noise voltage	$R_S = 20\ \Omega$	f = 1 kHz			$\text{nV}/\sqrt{\text{Hz}}$	
		f = 10 Hz to 10 kHz			$\mu\text{V}$	
$I_n$ Equivalent input noise current	$R_S = 20\ \Omega, f = 1\ \text{kHz}$	0.01			$\text{pA}/\sqrt{\text{Hz}}$	
THD Total harmonic distortion	$V_{rms} = 6\ \text{V}, f = 1\ \text{kHz}$	$A_{VD} = 1, R_S \leq 1\ \text{k}\Omega, R_L \geq 2\ \text{k}\Omega,$	0.003			%

\*On products compliant to MIL-PRF-38535, this parameter is not production tested.



**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
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operating characteristics,  $V_{CC\pm} = \pm 15\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR Slew rate at unity gain	$V_I = 10\text{ V}$ , $R_L = 2\text{ k}\Omega$ , $C_L = 100\text{ pF}$ , See Figure 1	8	13		$\text{V}/\mu\text{s}$
$t_r$ Rise time	$V_I = 20\text{ mV}$ , $R_L = 2\text{ k}\Omega$ , $C_L = 100\text{ pF}$ , See Figure 1		0.05		$\mu\text{s}$
Overshoot factor			20		%
$V_n$ Equivalent input noise voltage	$R_S = 20\ \Omega$	$f = 1\text{ kHz}$	18		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ Hz to } 10\text{ kHz}$	4		$\mu\text{V}$
$I_n$ Equivalent input noise current	$R_S = 20\ \Omega$ , $f = 1\text{ kHz}$		0.01		$\text{pA}/\sqrt{\text{Hz}}$
THD Total harmonic distortion	$V_{I\text{rms}} = 6\text{ V}$ , $f = 1\text{ kHz}$ , $A_{VD} = 1$ , $R_S \leq 1\text{ k}\Omega$ , $R_L \geq 2\text{ k}\Omega$ ,		0.003		%

**PARAMETER MEASUREMENT INFORMATION**

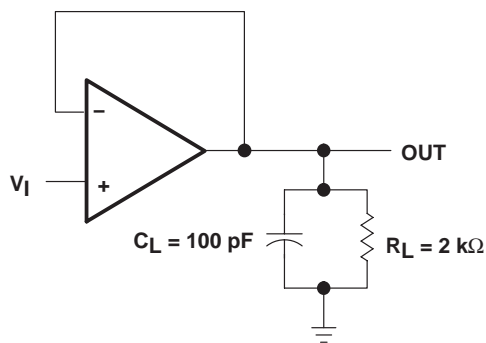


Figure 1

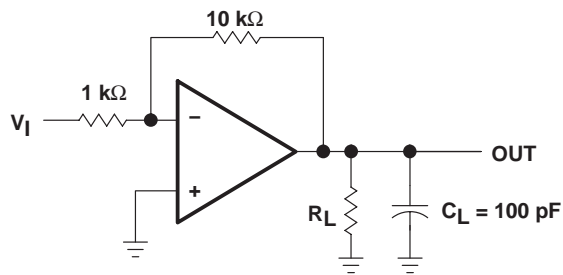


Figure 2

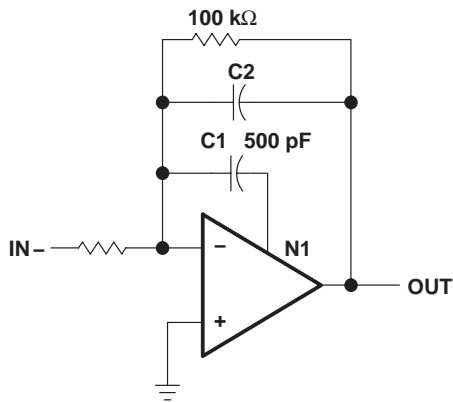


Figure 3

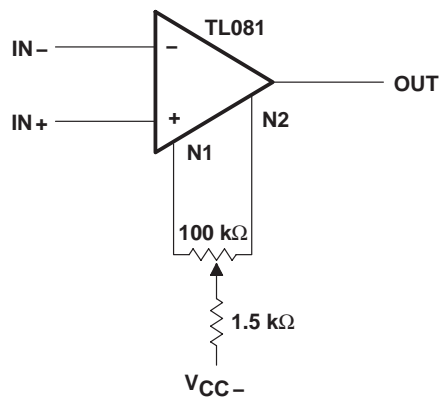


Figure 4

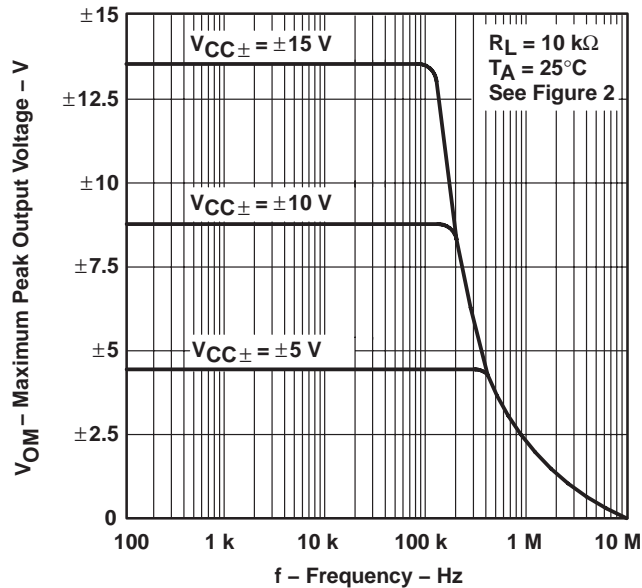


**TYPICAL CHARACTERISTICS**

**Table of Graphs**

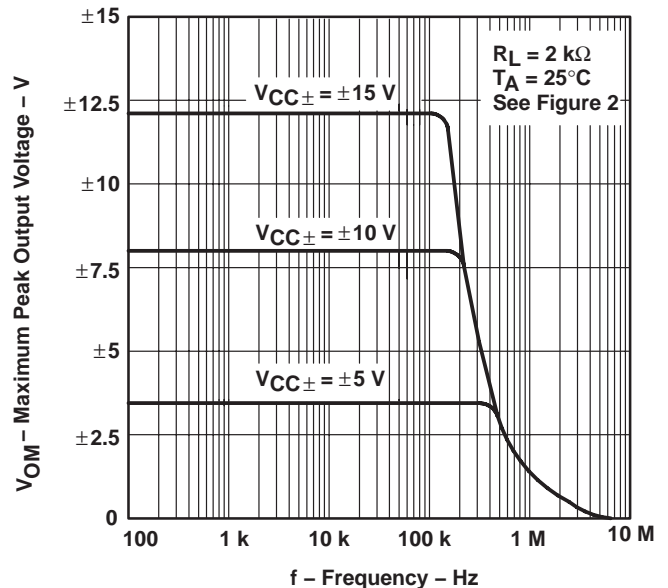
		FIGURE
V <sub>OM</sub>	Maximum peak output voltage	vs Frequency
		vs Free-air temperature
		vs Load resistance
		vs Supply voltage
AVD	Large-signal differential voltage amplification	vs Free-air temperature
		vs Frequency
	Differential voltage amplification	vs Frequency with feed-forward compensation
PD	Total power dissipation	vs Free-air temperature
I <sub>CC</sub>	Supply current	vs Free-air temperature
		vs Supply voltage
I <sub>IB</sub>	Input bias current	vs Free-air temperature
	Large-signal pulse response	vs Time
V <sub>O</sub>	Output voltage	vs Elapsed time
CMRR	Common-mode rejection ratio	vs Free-air temperature
V <sub>n</sub>	Equivalent input noise voltage	vs Frequency
THD	Total harmonic distortion	vs Frequency

**MAXIMUM PEAK OUTPUT VOLTAGE  
vs  
FREQUENCY**



**Figure 5**

**MAXIMUM PEAK OUTPUT VOLTAGE  
vs  
FREQUENCY**



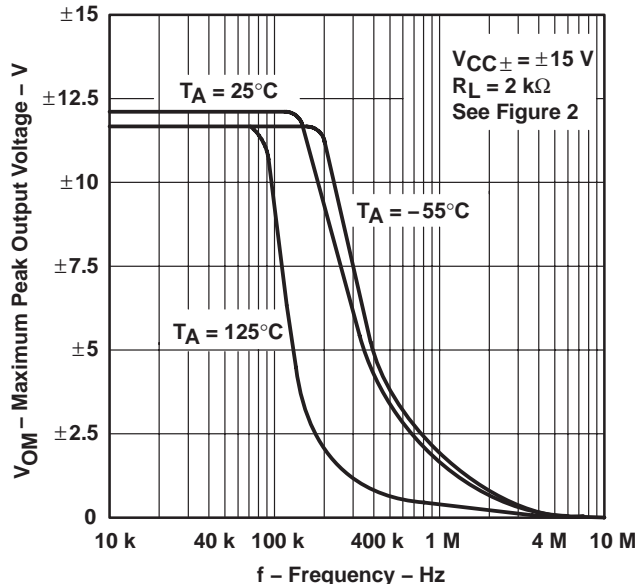
**Figure 6**

**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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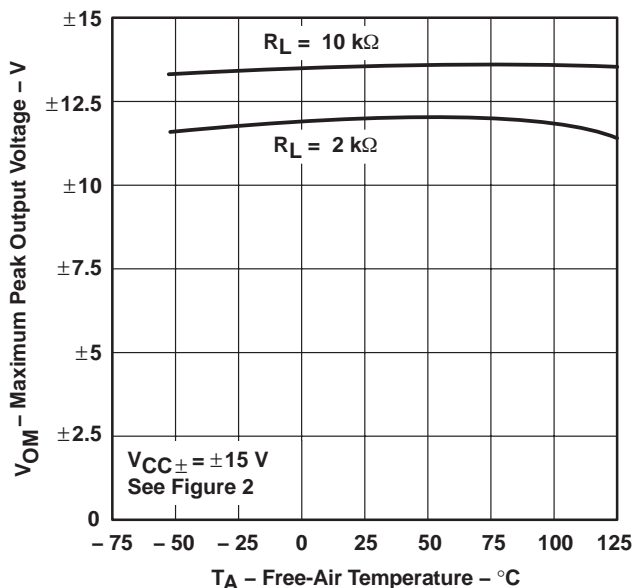
**TYPICAL CHARACTERISTICS†**

**MAXIMUM PEAK OUTPUT VOLTAGE  
vs  
FREQUENCY**



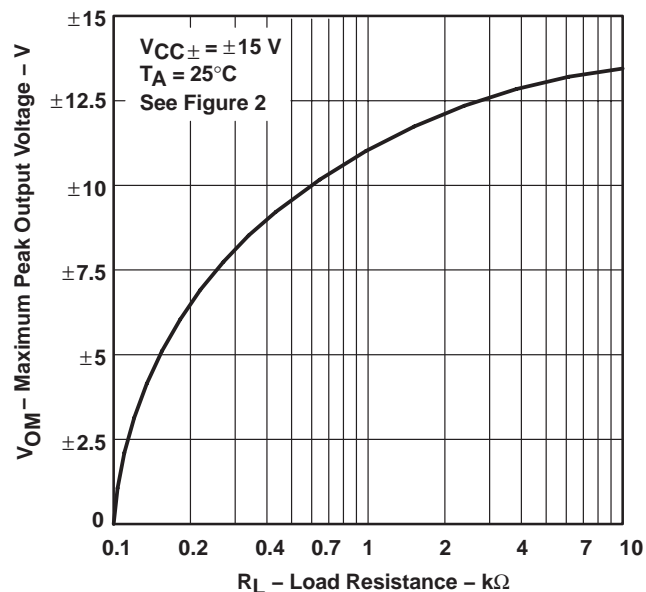
**Figure 7**

**MAXIMUM PEAK OUTPUT VOLTAGE  
vs  
FREE-AIR TEMPERATURE**



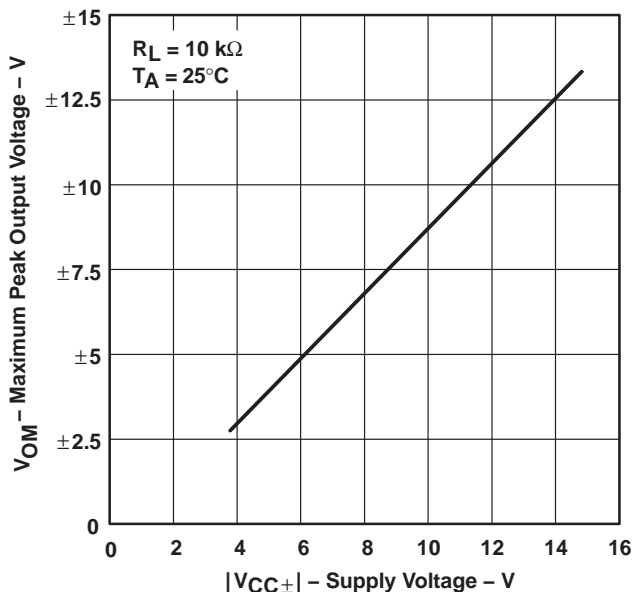
**Figure 8**

**MAXIMUM PEAK OUTPUT VOLTAGE  
vs  
LOAD RESISTANCE**



**Figure 9**

**MAXIMUM PEAK OUTPUT VOLTAGE  
vs  
SUPPLY VOLTAGE**



**Figure 10**

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



**TYPICAL CHARACTERISTICS†**

**LARGE-SIGNAL  
 DIFFERENTIAL VOLTAGE AMPLIFICATION  
 vs  
 FREE-AIR TEMPERATURE**

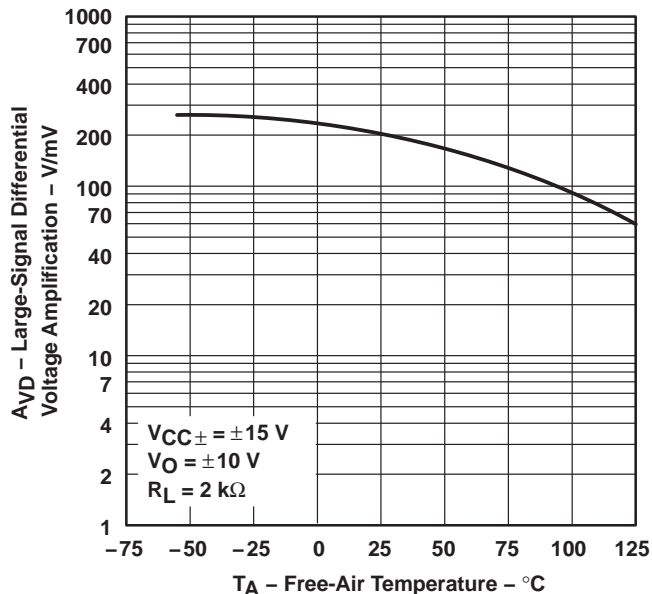


Figure 11

**LARGE-SIGNAL  
 DIFFERENTIAL VOLTAGE AMPLIFICATION  
 vs  
 FREQUENCY**

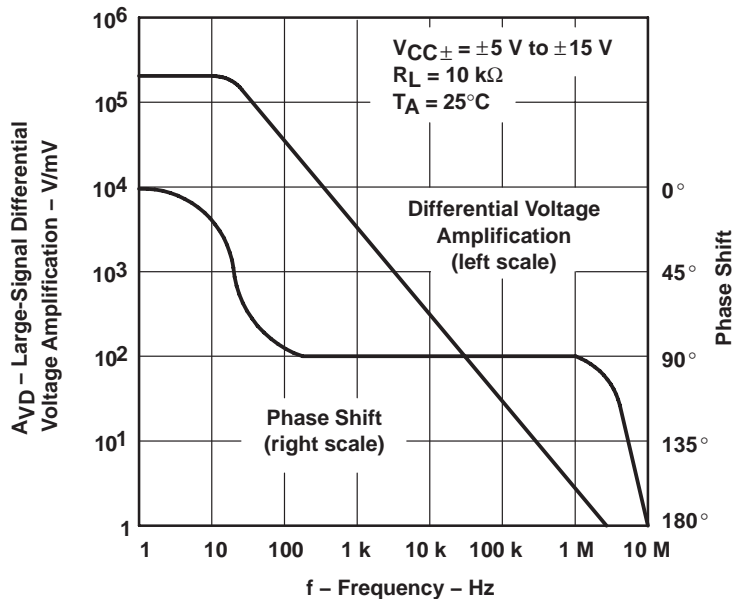


Figure 12

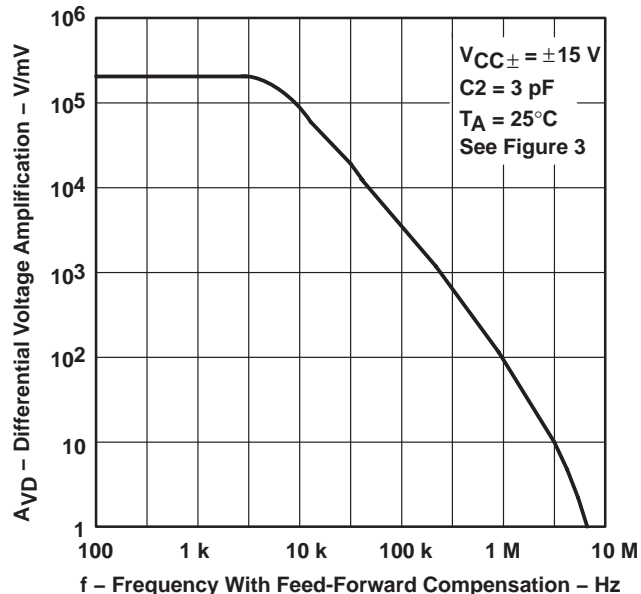
† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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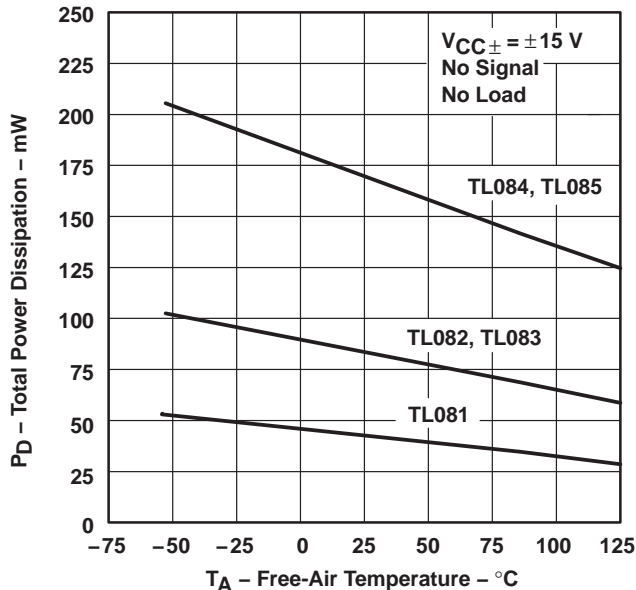
**TYPICAL CHARACTERISTICS†**

**DIFFERENTIAL VOLTAGE AMPLIFICATION  
vs  
FREQUENCY WITH FEED-FORWARD COMPENSATION**



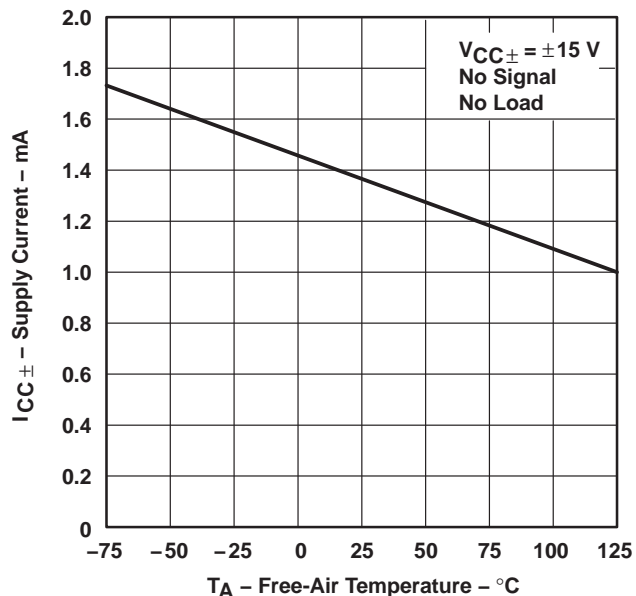
**Figure 13**

**TOTAL POWER DISSIPATION  
vs  
FREE-AIR TEMPERATURE**



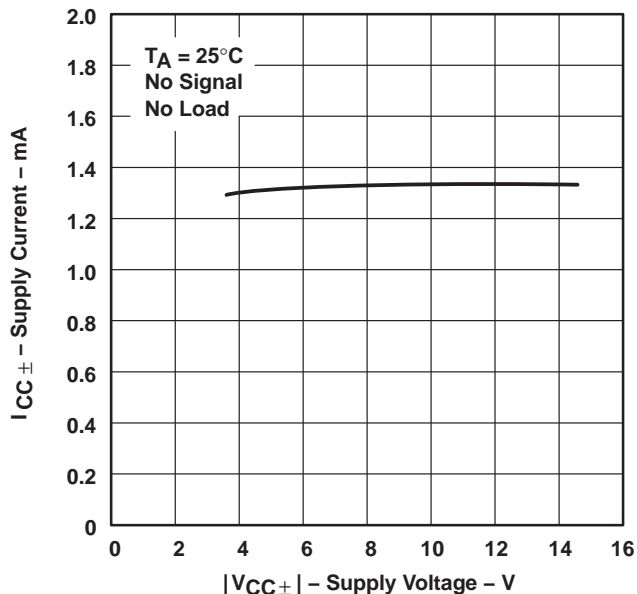
**Figure 14**

**SUPPLY CURRENT PER AMPLIFIER  
vs  
FREE-AIR TEMPERATURE**



**Figure 15**

**SUPPLY CURRENT  
vs  
SUPPLY VOLTAGE**

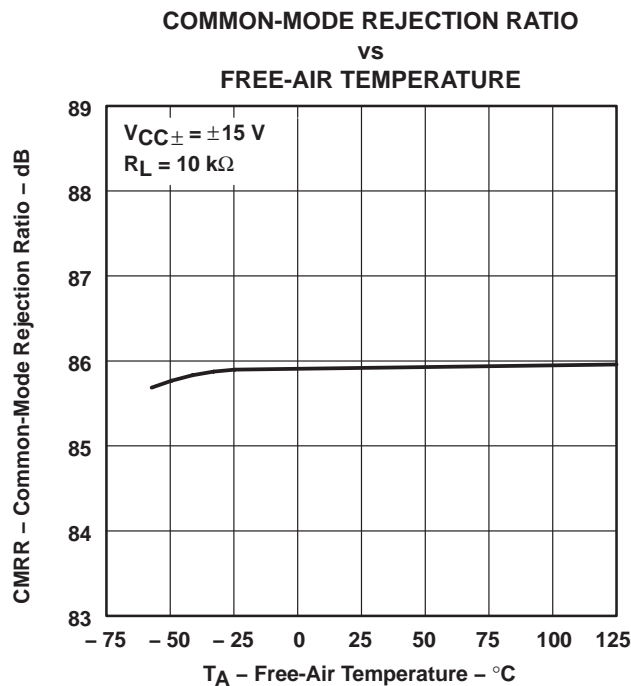
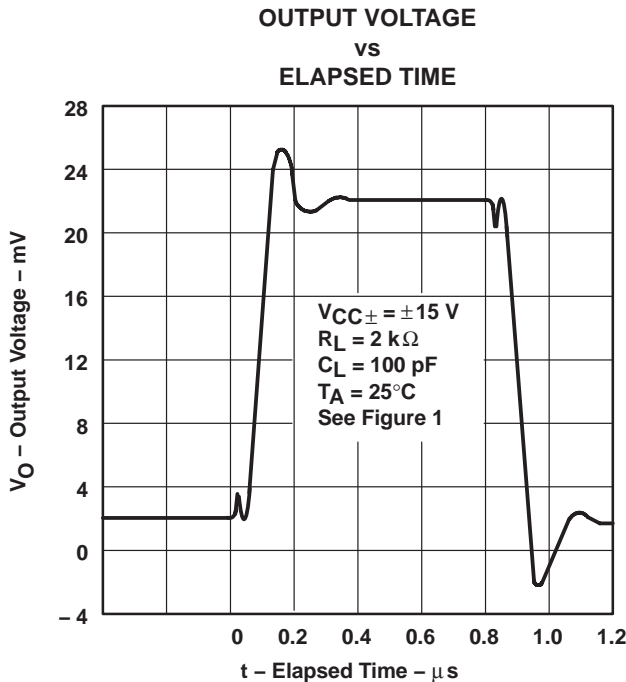
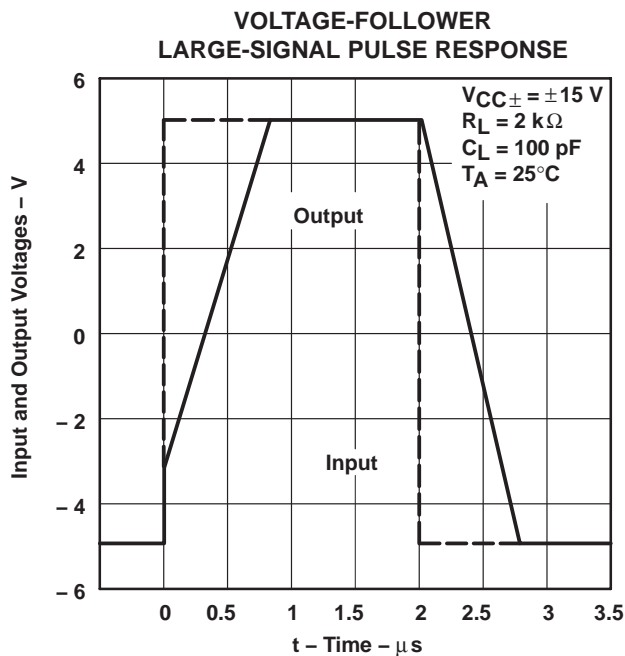
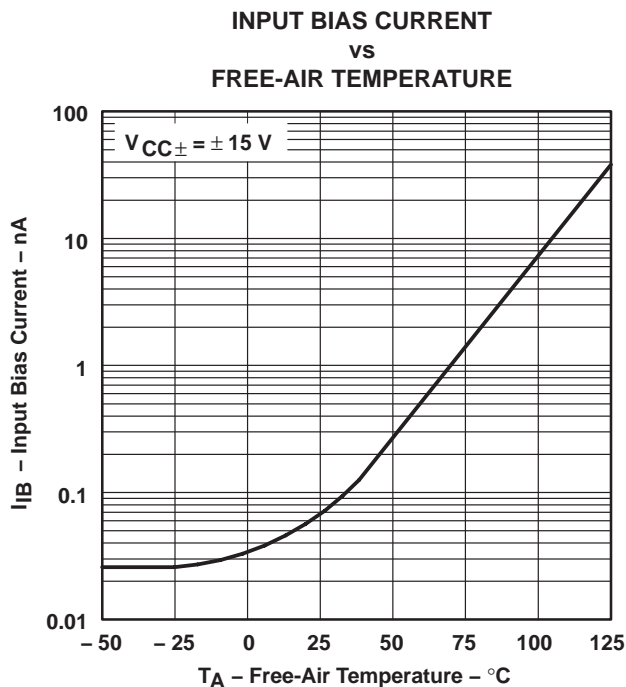


**Figure 16**

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



**TYPICAL CHARACTERISTICS†**



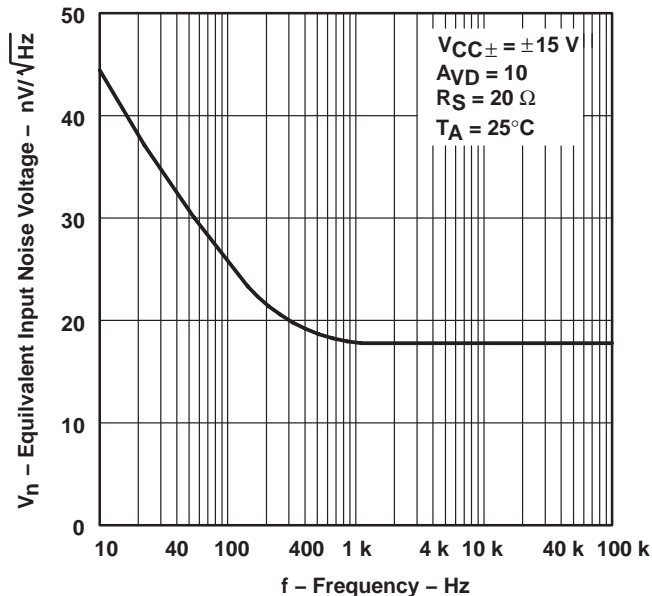
† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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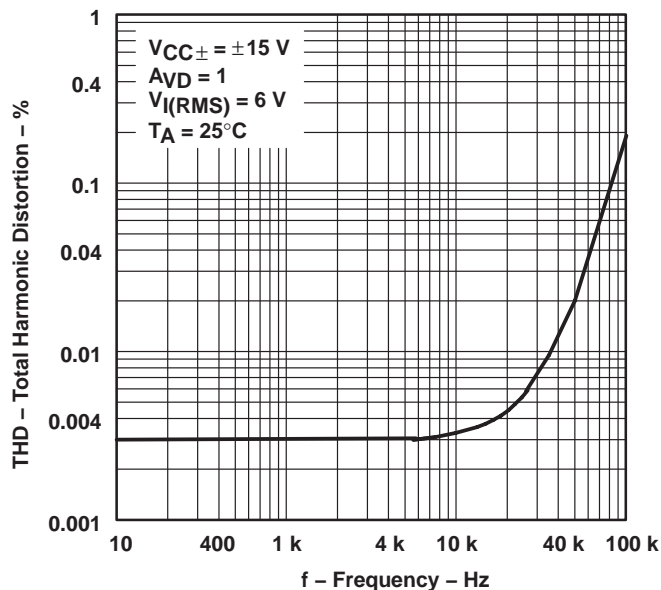
**TYPICAL CHARACTERISTICS†**

**EQUIVALENT INPUT NOISE VOLTAGE  
VS  
FREQUENCY**



**Figure 21**

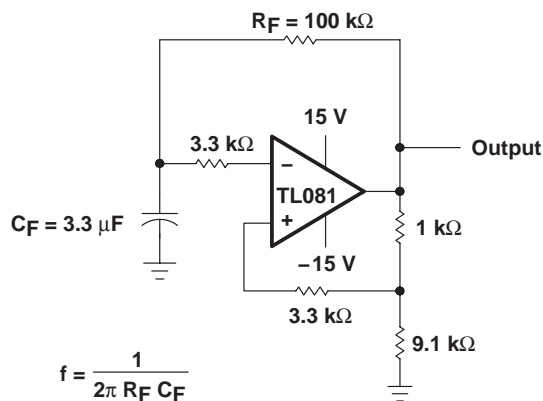
**TOTAL HARMONIC DISTORTION  
VS  
FREQUENCY**



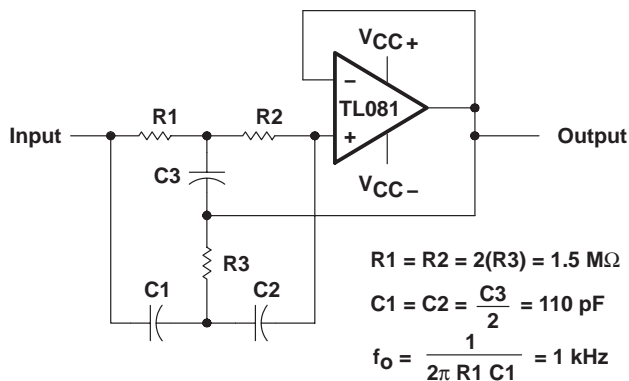
**Figure 22**

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

**APPLICATION INFORMATION**

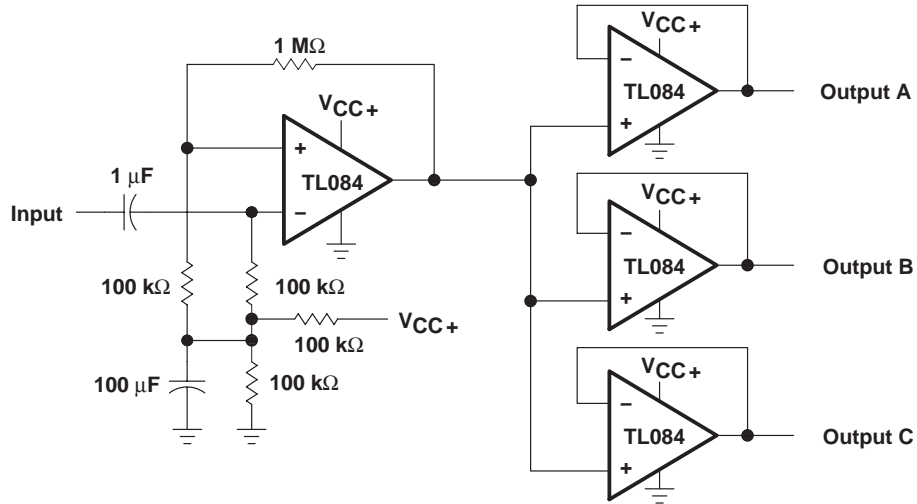


**Figure 23**

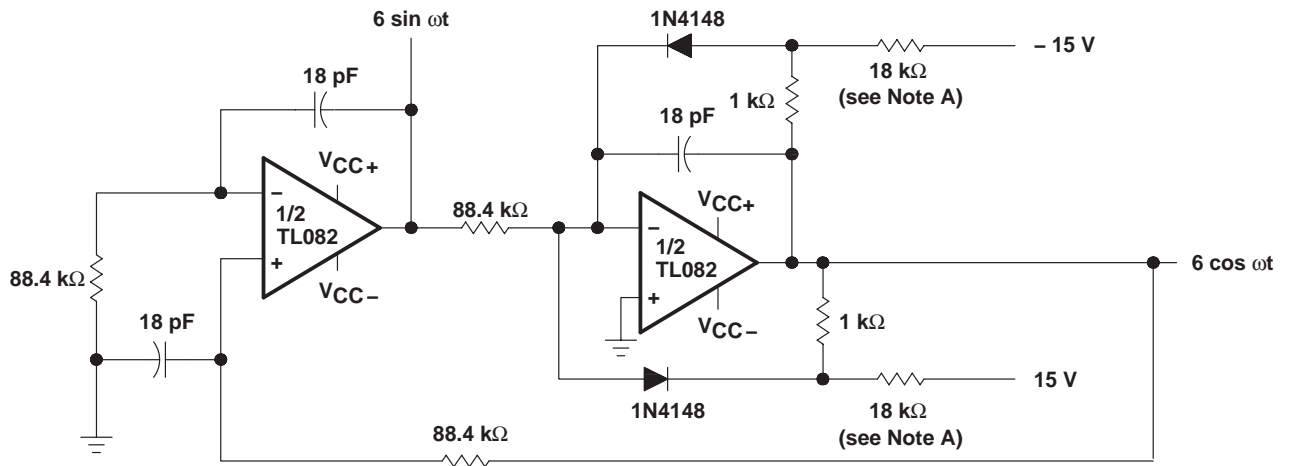


**Figure 24**

**APPLICATION INFORMATION**



**Figure 25. Audio-Distribution Amplifier**



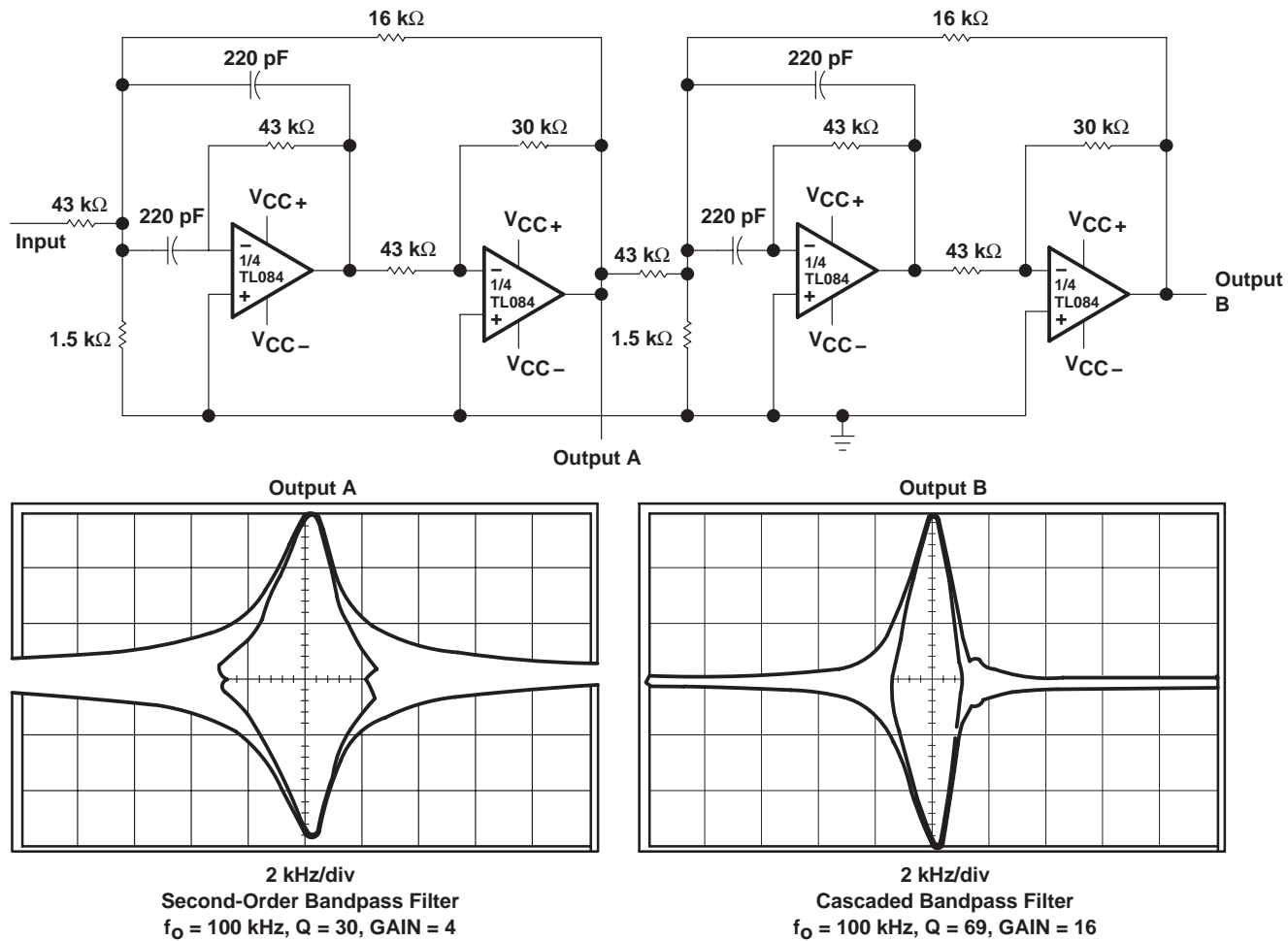
NOTE A: These resistor values may be adjusted for a symmetrical output.

**Figure 26. 100-KHz Quadrature Oscillator**

**TL081, TL081A, TL081B, TL082, TL082A, TL082B  
TL084, TL084A, TL084B  
JFET-INPUT OPERATIONAL AMPLIFIERS**

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**APPLICATION INFORMATION**



**Figure 27. Positive-Feedback Bandpass Filter**



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-9851501Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	-55 to 125	5962-9851501Q2A TL082MFKB	<a href="#">Samples</a>
5962-9851501QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9851501QPA TL082M	<a href="#">Samples</a>
5962-9851503Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	-55 to 125	5962-9851503Q2A TL084 MFKB	<a href="#">Samples</a>
5962-9851503QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	-55 to 125	5962-9851503QC A TL084MJB	<a href="#">Samples</a>
TL081ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081AC	<a href="#">Samples</a>
TL081ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081AC	<a href="#">Samples</a>
TL081ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081AC	<a href="#">Samples</a>
TL081ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081AC	<a href="#">Samples</a>
TL081ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081AC	<a href="#">Samples</a>
TL081ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081AC	<a href="#">Samples</a>
TL081ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	0 to 70		
TL081ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL081ACP	<a href="#">Samples</a>
TL081ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL081ACP	<a href="#">Samples</a>
TL081BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081BC	<a href="#">Samples</a>
TL081BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081BC	<a href="#">Samples</a>
TL081BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081BC	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL081BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081BC	<a href="#">Samples</a>
TL081BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081BC	<a href="#">Samples</a>
TL081BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	081BC	<a href="#">Samples</a>
TL081BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL081BCP	<a href="#">Samples</a>
TL081BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL081BCP	<a href="#">Samples</a>
TL081CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL081C	<a href="#">Samples</a>
TL081CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL081C	<a href="#">Samples</a>
TL081CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL081C	<a href="#">Samples</a>
TL081CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL081C	<a href="#">Samples</a>
TL081CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL081C	<a href="#">Samples</a>
TL081CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL081C	<a href="#">Samples</a>
TL081CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL081CP	<a href="#">Samples</a>
TL081CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL081CP	<a href="#">Samples</a>
TL081CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T081	<a href="#">Samples</a>
TL081CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T081	<a href="#">Samples</a>
TL081CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T081	<a href="#">Samples</a>
TL081CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70		
TL081ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL081I	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL081IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL081I	<a href="#">Samples</a>
TL081IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL081I	<a href="#">Samples</a>
TL081IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL081I	<a href="#">Samples</a>
TL081IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL081I	<a href="#">Samples</a>
TL081IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL081I	<a href="#">Samples</a>
TL081IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL081IP	<a href="#">Samples</a>
TL081IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL081IP	<a href="#">Samples</a>
TL081MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
TL081MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-55 to 125		
TL081MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-55 to 125		
TL082ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082AC	<a href="#">Samples</a>
TL082ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082AC	<a href="#">Samples</a>
TL082ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082AC	<a href="#">Samples</a>
TL082ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082AC	<a href="#">Samples</a>
TL082ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082AC	<a href="#">Samples</a>
TL082ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082AC	<a href="#">Samples</a>
TL082ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL082ACP	<a href="#">Samples</a>
TL082ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL082ACP	<a href="#">Samples</a>
TL082ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082A	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL082ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082A	<a href="#">Samples</a>
TL082ACPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082A	<a href="#">Samples</a>
TL082BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082BC	<a href="#">Samples</a>
TL082BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082BC	<a href="#">Samples</a>
TL082BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082BC	<a href="#">Samples</a>
TL082BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082BC	<a href="#">Samples</a>
TL082BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082BC	<a href="#">Samples</a>
TL082BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	082BC	<a href="#">Samples</a>
TL082BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL082BCP	<a href="#">Samples</a>
TL082BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL082BCP	<a href="#">Samples</a>
TL082CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL082C	<a href="#">Samples</a>
TL082CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL082C	<a href="#">Samples</a>
TL082CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL082C	<a href="#">Samples</a>
TL082CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL082C	<a href="#">Samples</a>
TL082CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL082C	<a href="#">Samples</a>
TL082CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL082C	<a href="#">Samples</a>
TL082CJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	0 to 70		
TL082CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL082CP	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL082CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL082CP	<a href="#">Samples</a>
TL082CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082CPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082CPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082CPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70		
TL082CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082CPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T082	<a href="#">Samples</a>
TL082ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL082I	<a href="#">Samples</a>
TL082IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL082I	<a href="#">Samples</a>
TL082IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL082I	<a href="#">Samples</a>
TL082IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL082I	<a href="#">Samples</a>
TL082IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL082I	<a href="#">Samples</a>
TL082IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL082I	<a href="#">Samples</a>
TL082IJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-40 to 85		
TL082IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL082IP	<a href="#">Samples</a>
TL082IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL082IP	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL082IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z082	<a href="#">Samples</a>
TL082IPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z082	<a href="#">Samples</a>
TL082IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z082	<a href="#">Samples</a>
TL082MFK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
TL082MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9851501Q2A TL082MFKB	<a href="#">Samples</a>
TL082MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	TL082MJG	<a href="#">Samples</a>
TL082MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9851501QPA TL082M	<a href="#">Samples</a>
TL084ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084AC	<a href="#">Samples</a>
TL084ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084AC	<a href="#">Samples</a>
TL084ACDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084AC	<a href="#">Samples</a>
TL084ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084AC	<a href="#">Samples</a>
TL084ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084AC	<a href="#">Samples</a>
TL084ACDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084AC	<a href="#">Samples</a>
TL084ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL084ACN	<a href="#">Samples</a>
TL084ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL084ACN	<a href="#">Samples</a>
TL084ACNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084A	<a href="#">Samples</a>
TL084ACNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084A	<a href="#">Samples</a>
TL084ACNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084A	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL084BCD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084BC	<a href="#">Samples</a>
TL084BCDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084BC	<a href="#">Samples</a>
TL084BCDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084BC	<a href="#">Samples</a>
TL084BCDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084BC	<a href="#">Samples</a>
TL084BCDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084BC	<a href="#">Samples</a>
TL084BCDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084BC	<a href="#">Samples</a>
TL084BCN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL084BCN	<a href="#">Samples</a>
TL084BCNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL084BCN	<a href="#">Samples</a>
TL084CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084C	<a href="#">Samples</a>
TL084CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084C	<a href="#">Samples</a>
TL084CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084C	<a href="#">Samples</a>
TL084CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084C	<a href="#">Samples</a>
TL084CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084C	<a href="#">Samples</a>
TL084CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084C	<a href="#">Samples</a>
TL084CJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
TL084CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL084CN	<a href="#">Samples</a>
TL084CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL084CN	<a href="#">Samples</a>
TL084CNSLE	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		
TL084CNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084	<a href="#">Samples</a>



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL084CNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL084	<a href="#">Samples</a>
TL084CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T084	<a href="#">Samples</a>
TL084CPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T084	<a href="#">Samples</a>
TL084CPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T084	<a href="#">Samples</a>
TL084CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	0 to 70		
TL084CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T084	<a href="#">Samples</a>
TL084CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T084	<a href="#">Samples</a>
TL084CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T084	<a href="#">Samples</a>
TL084ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL084I	<a href="#">Samples</a>
TL084IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL084I	<a href="#">Samples</a>
TL084IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL084I	<a href="#">Samples</a>
TL084IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL084I	<a href="#">Samples</a>
TL084IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL084I	<a href="#">Samples</a>
TL084IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL084I	<a href="#">Samples</a>
TL084IJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-40 to 85		
TL084IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL084IN	<a href="#">Samples</a>
TL084INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL084IN	<a href="#">Samples</a>
TL084MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	TL084MFK	<a href="#">Samples</a>
TL084MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9851503Q2A	<a href="#">Samples</a>



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
										TL084 MFKB	
TL084MJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	TL084MJ	<a href="#">Samples</a>
TL084MJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9851503QC A TL084MJB	<a href="#">Samples</a>
TL084QD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL084Q	<a href="#">Samples</a>
TL084QDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL084Q	<a href="#">Samples</a>
TL084QDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL084Q	<a href="#">Samples</a>
TL084QDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL084Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

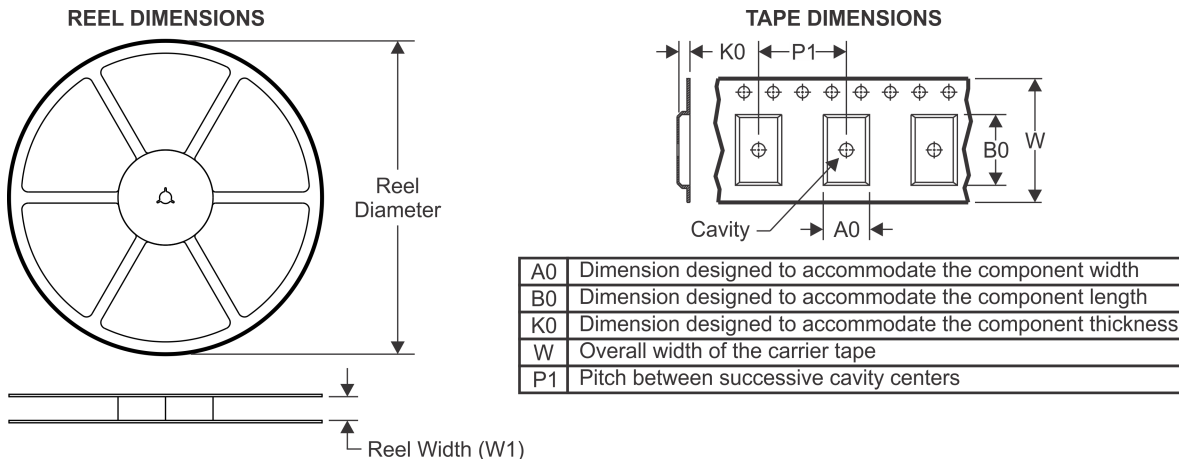
**OTHER QUALIFIED VERSIONS OF TL082, TL082M, TL084, TL084M :**

- Catalog: [TL082](#), [TL084](#)
- Automotive: [TL082-Q1](#), [TL082-Q1](#)
- Military: [TL082M](#), [TL084M](#)

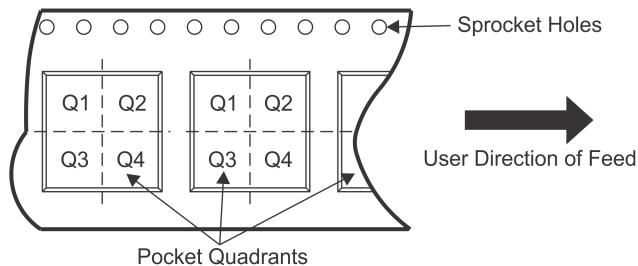
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

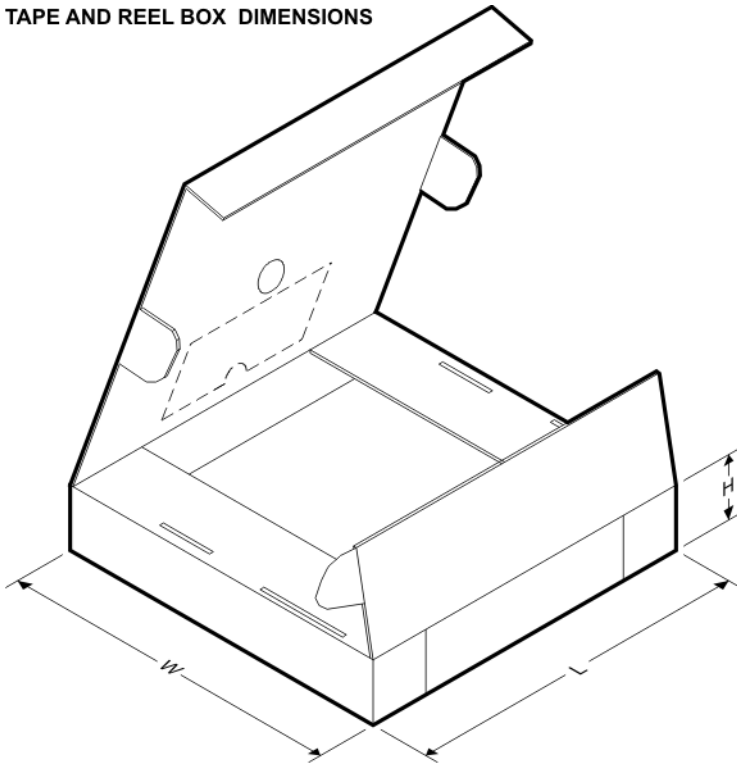


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL081ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL081BCDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL081CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL081CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL081IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082ACPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL082BCDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TL082CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL082IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL082IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL084ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084ACNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL084BCDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084CNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL084CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL084IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL084QDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL081ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL081BCDR	SOIC	D	8	2500	340.5	338.1	20.6
TL081CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL081CPSR	SO	PS	8	2000	367.0	367.0	38.0
TL081IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082ACDR	SOIC	D	8	2500	367.0	367.0	35.0
TL082ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082ACPSR	SO	PS	8	2000	367.0	367.0	38.0
TL082BCDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082CDR	SOIC	D	8	2500	367.0	367.0	35.0
TL082CPSR	SO	PS	8	2000	367.0	367.0	38.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL082CPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TL082IDR	SOIC	D	8	2500	367.0	367.0	35.0
TL082IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL082IPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TL084ACDR	SOIC	D	14	2500	333.2	345.9	28.6
TL084ACDR	SOIC	D	14	2500	367.0	367.0	38.0
TL084ACNSR	SO	NS	14	2000	367.0	367.0	38.0
TL084BCDR	SOIC	D	14	2500	333.2	345.9	28.6
TL084CDR	SOIC	D	14	2500	333.2	345.9	28.6
TL084CNSR	SO	NS	14	2000	367.0	367.0	38.0
TL084CPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TL084IDR	SOIC	D	14	2500	333.2	345.9	28.6
TL084QDR	SOIC	D	14	2500	367.0	367.0	38.0

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP1-T8

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



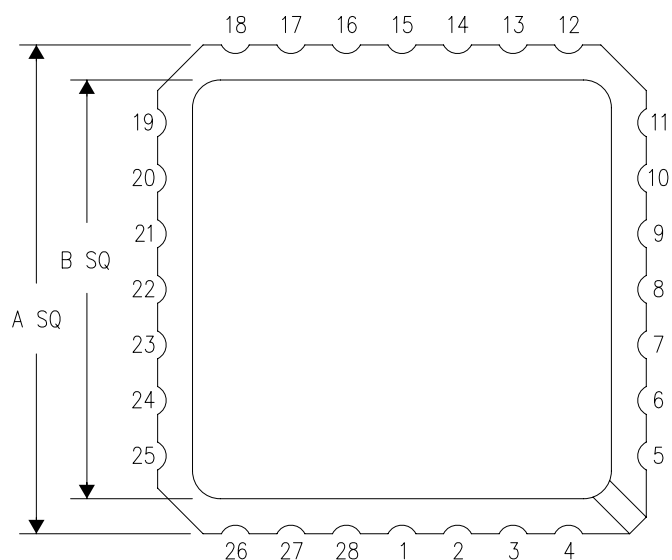
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

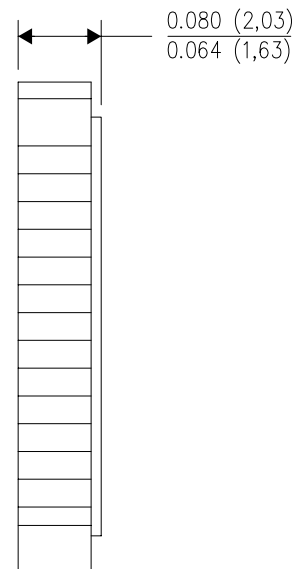
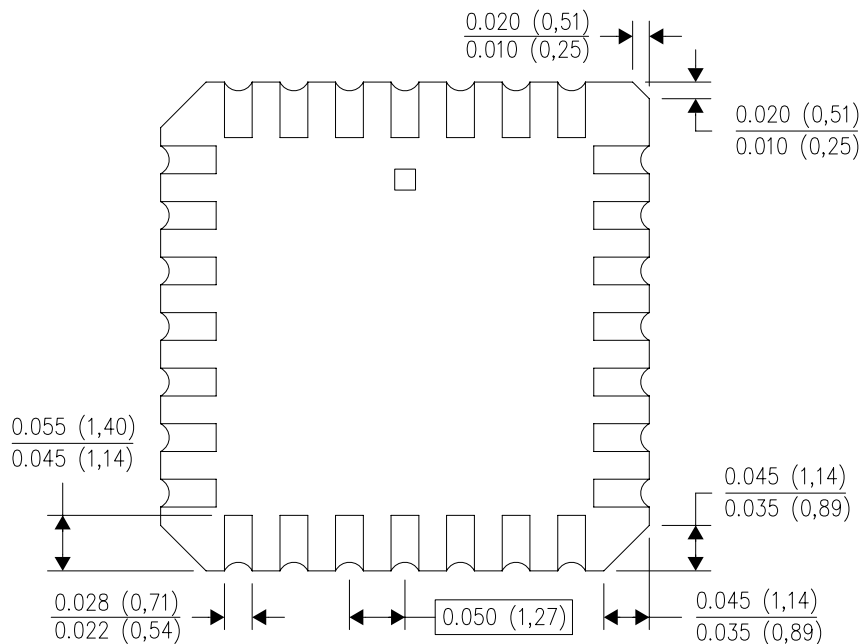
FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001 variation BA.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

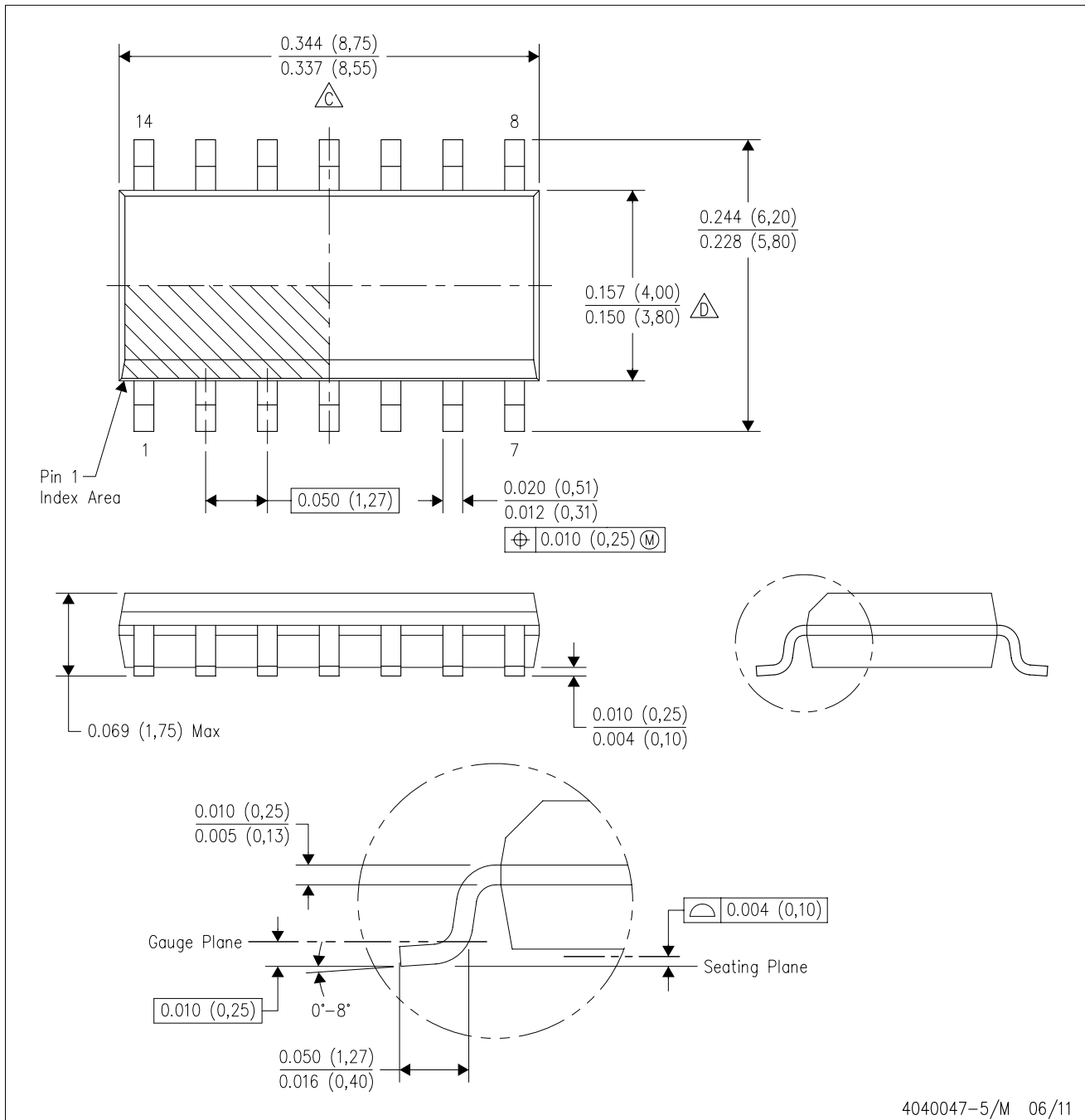


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

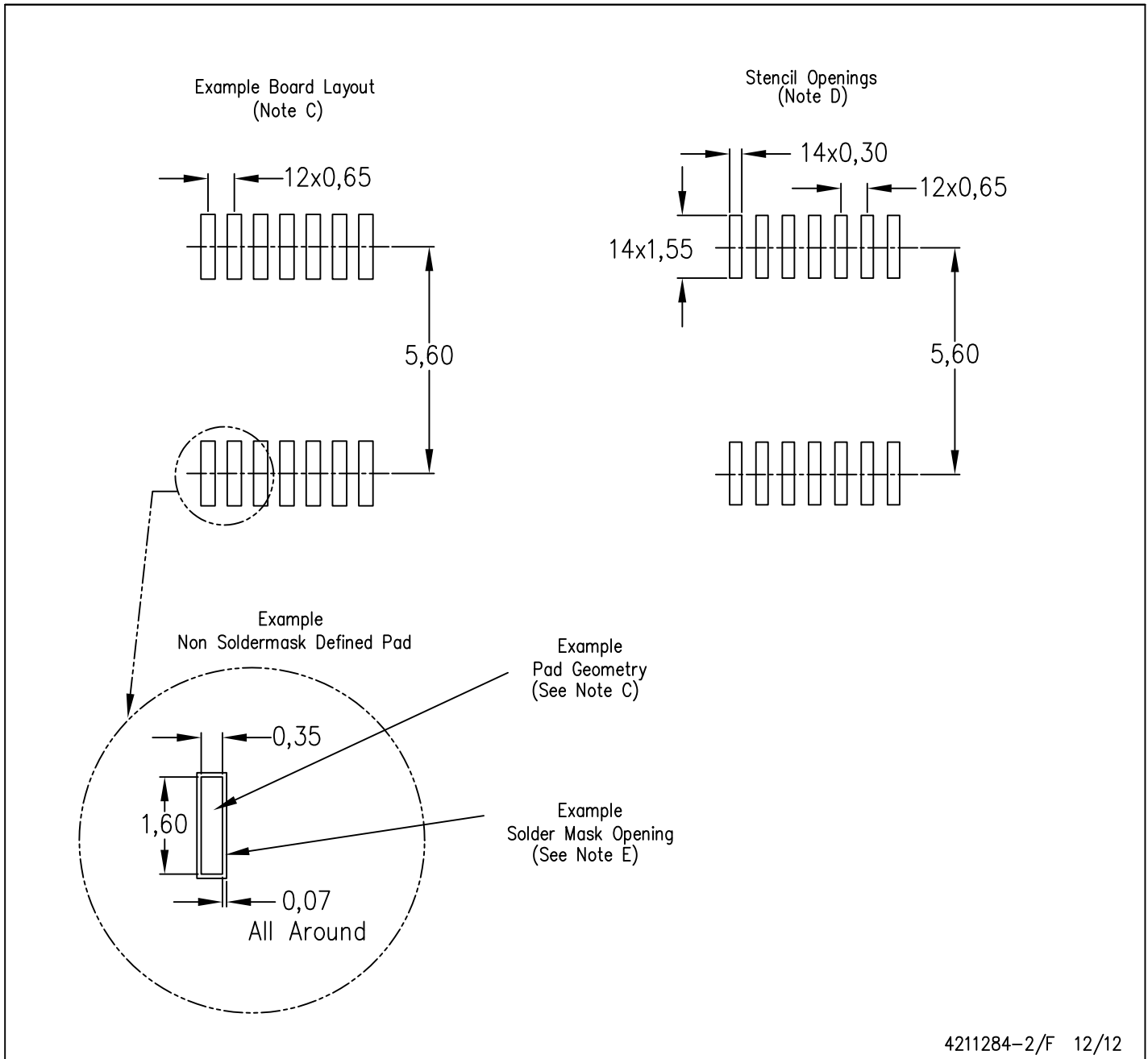
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

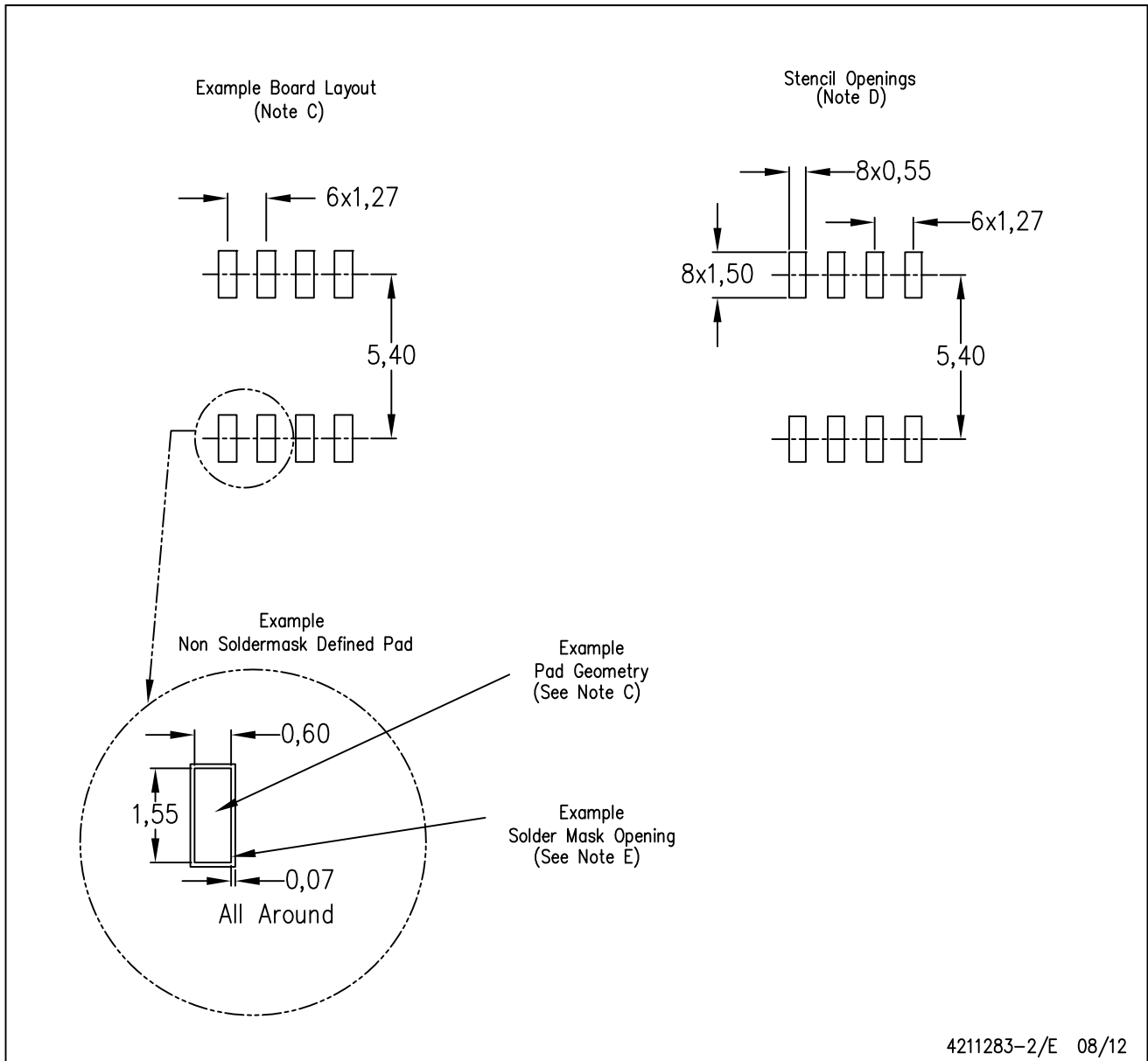


- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

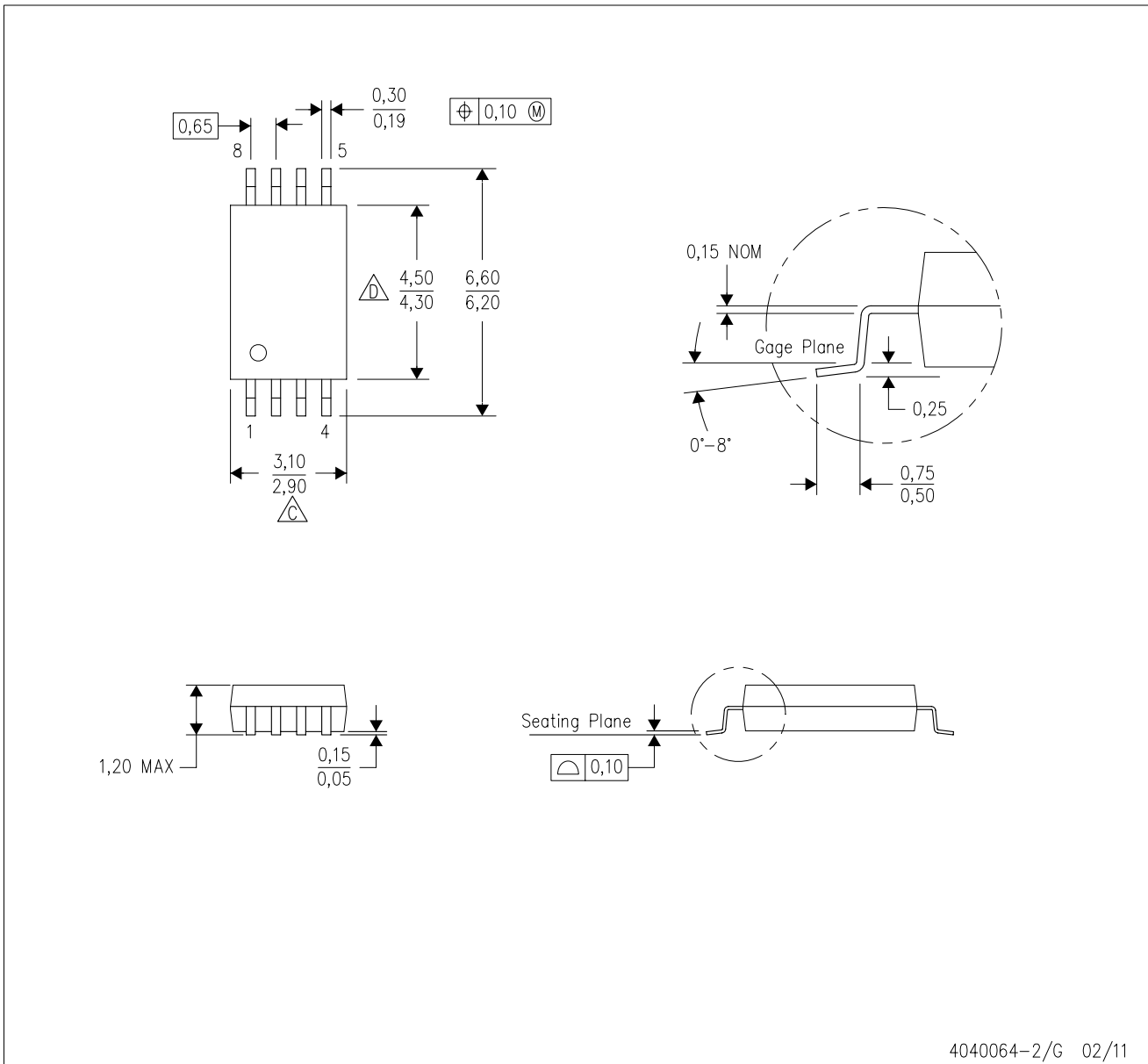
**14-PINS SHOWN**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

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Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
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